

2.5 V or 3.3 V, 200 MHz, 1:10 Clock Distribution Buffer

Features

- 2.5 V or 3.3 V operation
- 200 MHz clock support
- Two LVCMOS-/LVTTL-compatible inputs
- Ten clock outputs: drive up to 20 clock lines
- 1× or 1/2× configurable outputs
- Output three-state control
- 250-ps max output-to-output skew
- Pin-compatible with MPC946, MPC9446
- Available in commercial and industrial temperature range
- 32-pin TQFP package

Functional Description

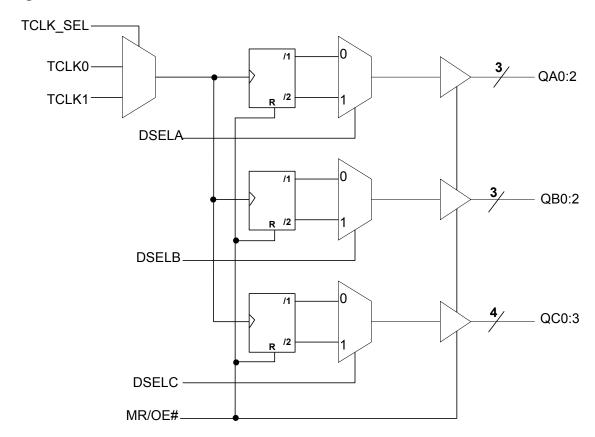
The CY29946 is a low-voltage 200-MHz clock distribution buffer with the capability to select one of two LVCMOS/LVTTL compatible input clocks. These clock sources can be used to provide for test clocks as well as the primary system clocks. All other control inputs are LVCMOS/LVTTL compatible. The 10 outputs are LVCMOS or LVTTL compatible and can drive $50~\Omega$ series or parallel terminated transmission lines. For series terminated transmission lines, each output can drive one or two traces giving the device an effective fanout of 1:20.

The CY29946 is capable of generating 1× and 1/2× signals from a 1× source. These signals are generated and retimed internally to ensure minimal skew between the 1× and 1/2× signals. SEL(A:C) inputs allow flexibility in selecting the ratio of 1× to1/2× outputs.

The CY29946 outputs can also be three-stated via MR/OE# input. When MR/OE# is set HIGH, it resets the internal flip-flops and three-states the outputs.

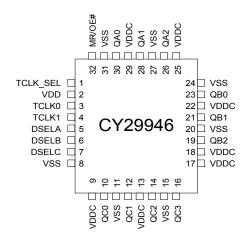
For a complete list of related documentation, click here.

Block Diagram





Pin Configuration



Pin Description

Pin	Name	PWR	I/O ^[1]	Description
3, 4	TCLK(0,1)		I, PU	External Reference/Test Clock Input
26, 28, 30	QA(2:0)	VDDC	0	Clock Outputs
19, 21, 23	QB(2:0)	VDDC	0	Clock Outputs
10, 12, 14, 16	QC(0:3)	VDDC	0	Clock Outputs
5, 6, 7	DSEL(A:C)		I, PD	Divider Select Inputs . When HIGH, selects ÷2 input divider. When LOW, selects ÷1 input divider.
1	TCLK_SEL		I, PD	TCLK Select Input. When LOW, TCLK0 clock is selected and when HIGH TCLK1 is selected.
32	MR/OE#		I, PD	Output Enable Input. When asserted LOW, the outputs are enabled and when asserted HIGH, internal flip-flops are reset and the outputs are three-stated. If more than 1 Bank is being used in /2 Mode, a reset must be performed (MR/OE# Asserted High) after power-up to ensure all internal flip-flops are set to the same state.
9, 13, 17, 18, 22, 25, 29	VDDC			2.5 V or 3.3 V Power Supply for Output Clock Buffers
2	VDD			2.5 V or 3.3 V Power Supply
8, 11, 15, 20, 24, 27, 31	VSS			Common Ground

Note

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^{1.} PD = Internal pull-down. PU = Internal pull-up.



Absolute Maximum Conditions[2]

Maximum Input Voltage Relative to V_{SS} V_{SS} – 0.3 V_{SS}
Maximum Input Voltage Relative to V_{DD} V_{DD} + 0.3 V_{DD}
Storage Temperature–65 $^{\circ}$ C to +150 $^{\circ}$ C
Operating Temperature40 °C to +85 °C
Maximum ESD protection2 kV
Maximum Power Supply5.5 V
Maximum Input Current±20 mA

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, V_{in} and V_{out} should be constrained to the range:

$$V_{SS} < (V_{in} \text{ or } V_{out}) < V_{DD}$$
.

Unused inputs must always be tied to an appropriate logic voltage level (either $\rm V_{SS}$ or $\rm V_{DD}).$

DC Electrical Specifications

 V_{DD} = V_{DDC} = 3.3 V ± 10% or 2.5 V ± 5%, over the specified temperature range

Parameter	Description	Conditions	Min	Тур	Max	Unit
V _{IL}	Input Low Voltage		V _{SS}	_	0.8	V
V _{IH}	Input High Voltage		2.0	-	V_{DD}	V
I _{IL}	Input Low Current ^[3]		_	-	-100	μA
I _{IH}	Input High Current ^[3]		_	-	100	μA
V_{OL}	Output Low Voltage ^[4]	I _{OL} = 20 mA	_	-	0.4	V
V _{OH}	Output High Voltage ^[4]	$I_{OH} = -20 \text{ mA}, V_{DD} = 3.3 \text{ V}$	2.5	-	_	V
		$I_{OH} = -20 \text{ mA}, V_{DD} = 2.5 \text{ V}$	1.8	-	_	
I _{DDQ}	Quiescent Supply Current		_	5	7	mA
I _{DD}	Dynamic Supply Current	V _{DD} = 3.3 V, Outputs @ 100 MHz, C _L = 30 pF	-	130	_	mA
		V_{DD} = 3.3 V, Outputs @ 160 MHz, C_L = 30 pF	_	225	_	
		V _{DD} = 2.5 V, Outputs @ 100 MHz, C _L = 30 pF	-	95	_	
		V _{DD} = 2.5 V, Outputs @ 160 MHz, C _L = 30 pF	-	160	_	
Z _{Out}	Output Impedance	V _{DD} = 3.3 V	12	15	18	W
		V _{DD} = 2.5 V	14	18	22	
C _{in}	Input Capacitance		_	4	_	pF

Thermal Resistance

Parameter [5]	Description	Test Conditions	32-pin TQFP	Unit
U/A	(junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, in	65	°C/W
- 30	Thermal resistance (junction to case)	accordance with EIA/JESD51.	12	°C/W

Notes

- 2. **Multiple Supplies:** The voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is not required.
- 3. Inputs have pull-up/pull-down resistors that effect input current.
- 4. Driving series or parallel terminated 50 Ω (or 50 Ω to $V_{DD}/2$) transmission lines.
- 5. These parameters are guaranteed by design and are not tested.



AC Electrical Specifications

 V_{DD} = V_{DDC} = 3.3 V ± 10% or 2.5 V ± 5%, over the specified temperature range^[6]

Parameter	Description	Conditions	Min	Тур	Max	Unit
F _{max}	Input Frequency ^[7]	V _{DD} = 3.3 V	_	_	200	MHz
		V _{DD} = 2.5 V	-	_	170	
T _{pd}	TTL_CLK To Q Delay[7]		5.0	_	11.5	ns
F _{outDC}	Output Duty Cycle ^[7, 8]	Measured at V _{DD} /2	45	-	55	%
t_{pZL}, t_{pZH}	Output enable time (all outputs)		2	_	10	ns
t_{pLZ}, t_{pHZ}	Output disable time (all outputs)		2	_	10	ns
T _{skew}	Output-to-Output Skew ^[7, 9]		-	150	250	ps
T _{skew(pp)}	Part-to-Part Skew ^[10]		_	2.0	4.5	ns
T _r /T _f	Output Clocks Rise/Fall Time ^[9]	0.8 V to 2.0 V, V _{DD} = 3.3 V	0.10	-	1.0	ns
		0.6 V to 1.8 V, V _{DD} = 2.5 V	0.10	_	1.3	

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<sup>Notes
Parameters are guaranteed by design and characterization. Not 100% tested in production. All parameters specified with loaded outputs.
Outputs driving 50Ω transmission lines.
50% input duty cycle.
See Figure 1 on page 5.
Part-to-Part skew at a given temperature and voltage.</sup>



Figure 1. LVCMOS_CLK CY29946 Test Reference for $\rm V_{CC}$ = 3.3 V and $\rm V_{CC}$ = 2.5 V

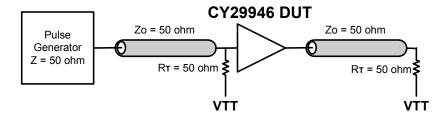


Figure 2. LVCMOS Propagation Delay (T_{PD}) Test Reference

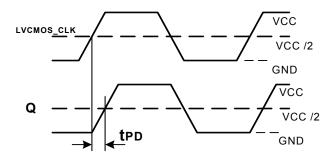


Figure 3. Output Duty Cycle (FoutDC)

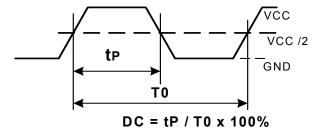
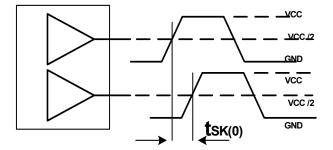


Figure 4. Output-to-Output Skew $t_{sk(0)}$



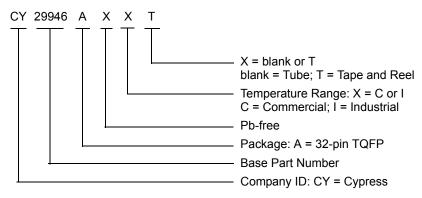
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Ordering Information

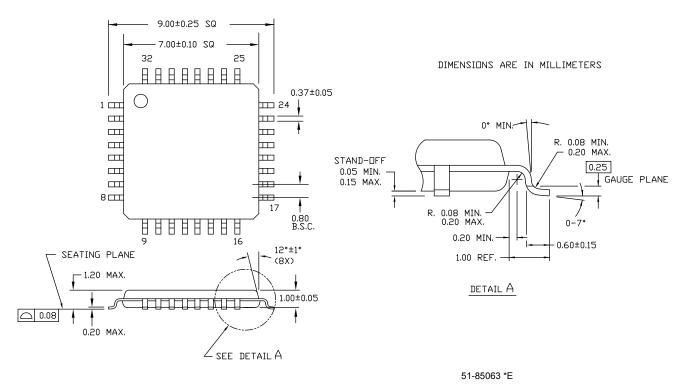
Part Number	Package Type	Production Flow
CY29946AXC	32-pin TQFP	Commercial, 0 °C to +70 °C
CY29946AXCT	32-pin TQFP – Tape and Reel	Commercial, 0 °C to +70 °C
CY29946AXI	32-pin TQFP	Industrial, –40 °C to +85 °C
CY29946AXIT	32-pin TQFP – Tape and Reel	Industrial, –40 °C to +85 °C

Ordering Code Definitions



Package Drawing and Dimensions

Figure 5. 32-pin TQFP 7 × 7 × 1.0 mm A3210



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Acronyms

Acronym	Description	
ESD	electrostatic discharge	
I/O	input/output	
LVCMOS low voltage complementary metal oxide semiconductor		
LVTTL	low-voltage transistor-transistor logic	
TQFP thin quad flat pack		

Document Conventions

Units of Measure

Symbol	Unit of Measure			
°C	legree Celsius			
kV	kilovolt			
MHz	megahertz			
μΑ	microampere			
mA	milliampere			
mm	millimeter			
mV	millivolt			
ns	nanosecond			
Ω	ohm			
%	percent			
pF	picofarad			
ps	picosecond			
V	volt			
W	watt			



Document History Page

	Document Title: CY29946, 2.5 V or 3.3 V, 200 MHz, 1:10 Clock Distribution Buffer Document Number: 38-07286					
Rev.	ECN No.	Orig. of Change	Issue Date	Description of Change		
**	111097	BRK	02/07/02	New data sheet.		
*A	116780	HWT	08/15/02	Added the commercial temperature range in the Ordering Information		
*B	122878	RBI	12/22/02	Added power-up requirements to Maximum Ratings		
*C	130007	RGL	10/15/03	Fixed the block diagram. Fixed the MK/OE# description in the pin description table.		
*D	131375	RGL	11/21/03	Updated document history page (revision *C) to reflect changes that were not listed.		
*E	221587	RGL	See ECN	Minor Change: Moved up the word Block Diagram in the first page.		
*F	2899714	BRIJ / CXQ	03/26/10	Updated Ordering Information: Updated part numbers. Updated Package Drawing and Dimensions.		
*G	3254185	CXQ	05/11/2011	Added Ordering Code Definitions. Added Acronyms and Units of Measure. Updated to new template.		
*H	4389717	XHT	05/30/2014	Updated Package Drawing and Dimensions: spec 51-85063 – Changed revision from *C to *D. Completing Sunset Review.		
*	4586288	XHT	12/03/2014	Updated Functional Description: Added "For a complete list of related documentation, click here." at the end.		
*J	5270507	PSR	05/13/2016	Added Thermal Resistance. Updated Package Drawing and Dimensions: spec 51-85063 – Changed revision from *D to *E. Updated to new template.		
*K	5754145	XHT	05/29/2017	Updated to new template. Completing Sunset Review.		



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